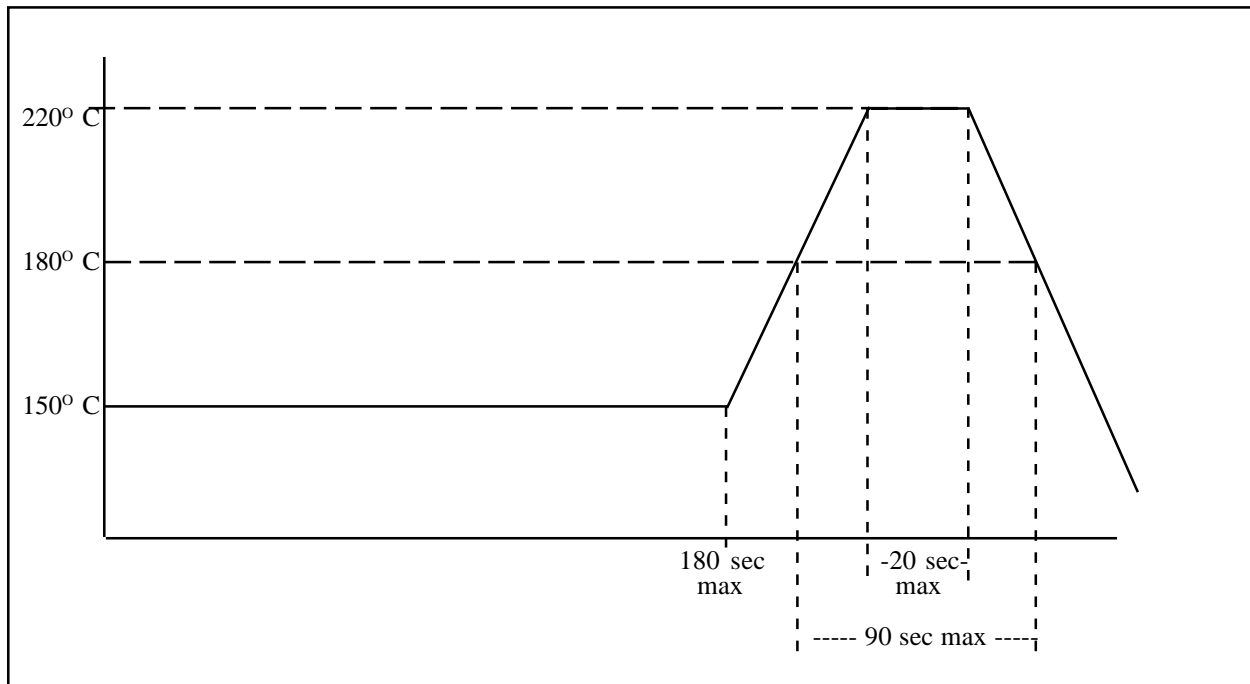

XECOM APPLICATION NOTE:

Soldering Instructions for Hybrid PLCC Products

Xecom's Hybrid PLCC products including the XE2420 and XE5620 modems and XE056JLHGU DAA are subject to damage if exposed to too much heat during solder reflow operations. The soldering instructions below will ensure that the process of soldering the module to the board does not damage the module. At no time should the maximum temperatures be exceeded.

Maximum Temperature	220° C
Maximum Time at 220° C	20 Seconds
Maximum Time above Eutectic (180° C)	90 Seconds
Maximum Preheat Dwell Time	180 Seconds

Maximum Recommended Solder Profile



Notes:

Because of their large black bodies, Xecom's Hybrid PLCC products must not be exposed to direct Infrared Ray (IR) heating. If your process includes direct IR heating, you must shield the PLCC DAA module from the infrared rays.

Xecom's Hybrid PLCC modules should be exposed to no more than one reflow cycle.